



Product Model 6496:
For MCM/Hybrid, Silver Glass and Eutectic die attach

MAT – MicroAssembly Technologies, Ltd.
Product Model 6497

Performs Silver Glass, Eutectic and Ultrasonic assemblies in addition to MCM/Hybrid/COB.

Similar table top design like the 6495, includes additional accessories and software capabilities required for the Silver Glass/Eutectic/Ultrasonic processes.

Software control of Bond Line Thickness, Scrubbing parameters and Ultrasonic parameters.

Pick from 2" or 4" Waffle or Gel-Pak.

Pick from Wafers up to 8" (automatic or manual).

Wafer Mapping capability or Ink Dot recognition.

Eutectic, inert gas cover, high temperature process control.

Accurate Bond Line Thickness control based on the measurement of the substrate height.

Dispensing and stamping (Pin Transfer) of a wide range of adhesives including Epoxies, UV adhesives, RTV's, Silver Glass, etc.

Ideal for low to medium volume production.

